



Part Number : 787261054

Series Number : 78726


Product Category : Memory Module Connectors

Product Description : DDR4 DIMM Socket, Vertical Through-Hole, 0.76µm Gold Plating, 288 Circuits, PCB Thickness 1.57mm, Tail Length 2.10mm, White Housing, White Latch
Status : New Business Not Supported

Documents & Resources

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2024)4144-DC (27 June 2024)
EU RoHS	Compliant per EU 2015/863

Multiple Part Product Compliance Statements

- Eu RoHS
- REACH SVHC
- Low-Halogen

Multiple Part Industry Compliance Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

EU RoHS Certificate of Compliance

Part Details

General

Status	New Business Not Supported
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Category	Memory Module Connectors
Series	78726
Description	DDR4 DIMM Socket, Vertical Through-Hole, 0.76µm Gold Plating, 288 Circuits, PCB Thickness 1.57mm, Tail Length 2.10mm, White Housing, White Latch
Component Type	Socket
JEDEC Outline	MO-309
Product Family	DDR4 DIMM Sockets
Product Name	DDR4 DIMM
UPC	889056151276

Agency

CSA	LR19980
UL	E29179

Electrical

Current - Maximum per Contact	0.75A
Voltage - Maximum	29V AC (RMS)/DC

Physical

Circuits (Loaded)	288
Circuits (maximum)	288
Durability (mating cycles max)	25
Entry Angle	Vertical (Top Entry)
Flammability	94V-0
Housing Color	White
Keying to Mating Part	None
Latch Color	White
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	Nylon
Net Weight	6.561/g
Packaging Type	Tray

PC Tail Length	2.10mm
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness - Recommended	1.57mm
Pitch - Mating Interface	0.85mm
Pitch - Termination Interface	0.85mm
Plating min - Mating	0.762µm
Plating min - Termination	2.540µm
Temperature Range - Operating	-55° to +85°C
Termination Interface Style	Through Hole

Solder Process Data

Max-Duration	5
Lead-Free Process Capability	SMC&WAVE
Max-Cycle	2
Max-Temp	260

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